

Smart Dual Lowside Power Switch

Features

- Logic Level Input
- Input Protection (ESD)
- Thermal shutdown with auto restart
- Overload protection
- Short circuit protection
- Overvoltage protection
- Current limitation
- Analog driving possible

Product Summary

Drain source voltage	V_{DS}	42	V
On-state resistance	$R_{DS(on)}$	200	m Ω
Nominal load current	$I_{D(Nom)}$	1.3	A
Clamping energy	E_{AS}	150	mJ



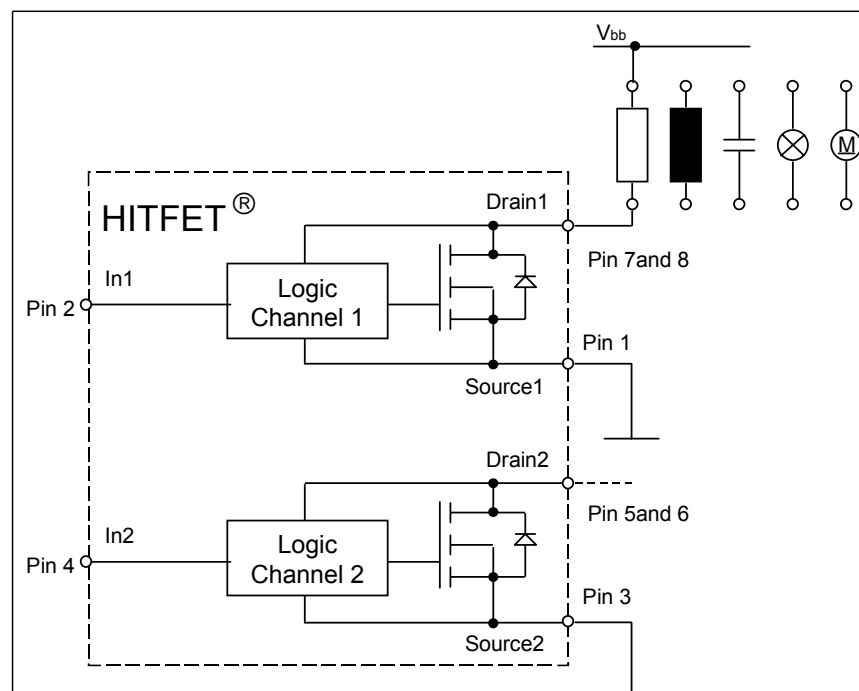
P-DSO-8

Application

- All kinds of resistive, inductive and capacitive loads in switching or linear applications
- μ C compatible power switch for 12 V DC applications
- Replaces electromechanical relays and discrete circuits

General Description

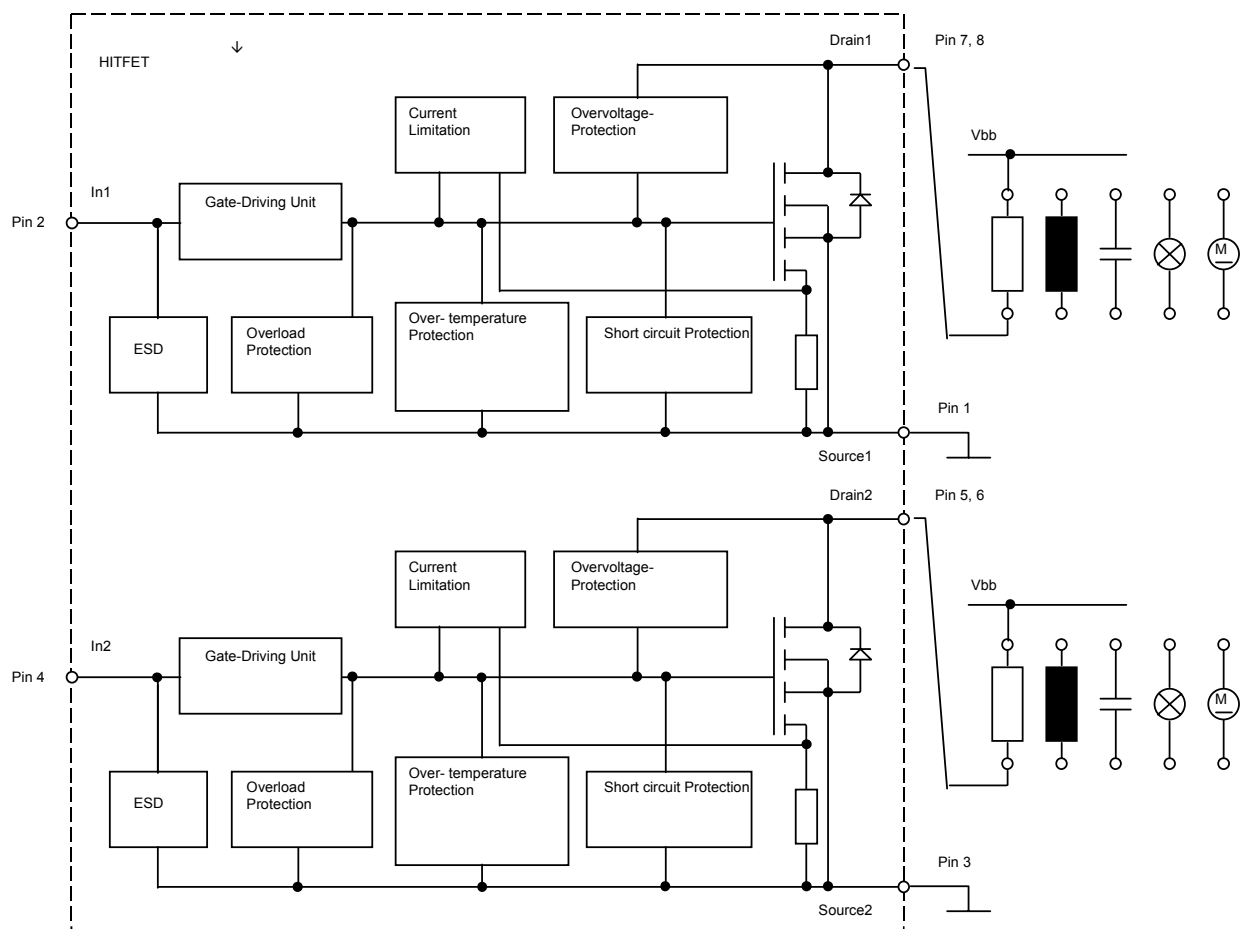
N channel vertical power FET in Smart SIPMOS® technology. Fully protected by embedded protection functions.



Pin Description

Pin	Symbol	Function
1	S1	Source Channel 1
2	IN1	Input Channel 1
3	S2	Source Channel 2
4	IN2	Input Channel 2
5	D2	Drain Channel 2
6	D2	Drain Channel 2
7	D1	Drain Channel 1
8	D1	Drain Channel 1

Pin Configuration (Top view)



Maximum Ratings at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	42	V
Drain source voltage for short circuit protection ¹⁾ $T_j = -40 \dots 150^\circ\text{C}$	$V_{DS(SC)}$	18	
Continuous input current ¹⁾ $-0.2\text{V} \leq V_{IN} \leq 10\text{V}$ $V_{IN} < -0.2\text{V}$ or $V_{IN} > 10\text{V}$	I_{IN}	no limit $ I_{IN} \leq 2$	mA
Operating temperature	T_j	$-40 \dots +150$	$^\circ\text{C}$
Storage temperature	T_{stg}	$-55 \dots +150$	
Power dissipation ²⁾ $T_A = 85^\circ\text{C}$	P_{tot}	0.8	W
Unclamped single pulse inductive energy ¹⁾ each channel	E_{AS}	150	mJ
Load dump protection $V_{LoadDump}^{1)3)} = V_A + V_S$ $V_{IN} = 0$ and 10V , $t_d = 400\text{ms}$, $R_I = 2\Omega$, $R_L = 9\Omega$, $V_A = 13.5\text{V}$	V_{LD}	50	V
Electrostatic discharge voltage (Human Body Model) according to MIL STD 883D, method 3015.7 and EOS/ESD assn. standard S5.1 - 1993	V_{ESD}	2	kV
DIN humidity category, DIN 40 040		E	
IEC climatic category; DIN IEC 68-1		40/150/56	

Thermal resistance

junction - ambient: per channel	R_{thJA}	100	K/W
@ 6cm^2 cooling area ²⁾ one channel on			
both channels on		160	

¹⁾not subject to production test, specified by design

²⁾Device on $50\text{mm} \times 50\text{mm} \times 1.5\text{mm}$ epoxy PCB FR4 with 6cm^2 (one layer, $70\mu\text{m}$ thick) copper area for drain connection. PCB mounted vertical without blown air.

³⁾ $V_{Loaddump}$ is setup without the DUT connected to the generator per ISO 7637-1 and DIN 40839

Electrical Characteristics

Parameter at $T_j = 25^{\circ}\text{C}$, unless otherwise specified	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Drain source clamp voltage $T_j = -40 \dots +150$, $I_D = 10 \text{ mA}$	$V_{\text{DS(AZ)}}$	42	-	55	V
Off-state drain current $T_j = -40 \dots +150^{\circ}\text{C}$ $V_{\text{DS}} = 32 \text{ V}$, $V_{\text{IN}} = 0 \text{ V}$	I_{DSS}	-	1.5	10	μA
Input threshold voltage $I_D = 0.15 \text{ mA}$, $T_j = 25^{\circ}\text{C}$ $I_D = 0.15 \text{ mA}$, $T_j = 150^{\circ}\text{C}$	$V_{\text{IN(th)}}$	1.3 0.8	1.7 -	2.2 -	V
On state input current	$I_{\text{IN(on)}}$	-	10	30	μA
On-state resistance $V_{\text{IN}} = 5 \text{ V}$, $I_D = 1.4 \text{ A}$, $T_j = 25^{\circ}\text{C}$ $V_{\text{IN}} = 5 \text{ V}$, $I_D = 1.4 \text{ A}$, $T_j = 150^{\circ}\text{C}$	$R_{\text{DS(on)}}$	- -	190 350	240 480	$\text{m}\Omega$
On-state resistance $V_{\text{IN}} = 10 \text{ V}$, $I_D = 1.4 \text{ A}$, $T_j = 25^{\circ}\text{C}$ $V_{\text{IN}} = 10 \text{ V}$, $I_D = 1.4 \text{ A}$, $T_j = 150^{\circ}\text{C}$	$R_{\text{DS(on)}}$	- -	150 280	200 400	
Nominal load current per channel ¹⁾ $V_{\text{DS}} = 0.5 \text{ V}$, $T_j < 150^{\circ}\text{C}$, $V_{\text{IN}} = 10 \text{ V}$, $T_{\text{A}} = 85^{\circ}\text{C}$, one channel on both channels on	$I_{\text{D(Nom)}}$	1.3 1	1.65 1.3	- -	A
Current limit (active if $V_{\text{DS}} > 2.5 \text{ V}$) ²⁾ $V_{\text{IN}} = 10 \text{ V}$, $V_{\text{DS}} = 12 \text{ V}$, $t_{\text{m}} = 200 \mu\text{s}$	$I_{\text{D(lim)}}$	5	7.5	10	

¹⁾not subject to production test, specified by design

²⁾Device switched on into existing short circuit (see diagram Determination of $I_{D(lim)}$). If the device is in on condition and a short circuit occurs, these values might be exceeded for max. 50 μs .

Electrical Characteristics

Parameter at $T_j = 25^\circ\text{C}$, unless otherwise specified	Symbol	Values			Unit
		min.	typ.	max.	

Dynamic Characteristics

Turn-on time V_{IN} to 90% I_D : $R_L = 4.7\ \Omega$, $V_{IN} = 0$ to 10 V, $V_{bb} = 12$ V	t_{on}	-	45	100	μs
Turn-off time V_{IN} to 10% I_D : $R_L = 4.7\ \Omega$, $V_{IN} = 10$ to 0 V, $V_{bb} = 12$ V	t_{off}	-	60	100	
Slew rate on 70 to 50% V_{bb} : $R_L = 4.7\ \Omega$, $V_{IN} = 0$ to 10 V, $V_{bb} = 12$ V	$-dV_{DS}/dt_{on}$	-	0.4	1.5	$\text{V}/\mu\text{s}$
Slew rate off 50 to 70% V_{bb} : $R_L = 4.7\ \Omega$, $V_{IN} = 10$ to 0 V, $V_{bb} = 12$ V	dV_{DS}/dt_{off}	-	0.6	1.5	

Protection Functions¹⁾

Thermal overload trip temperature	T_{jt}	150	175	-	$^\circ\text{C}$
Thermal hysteresis	ΔT_{jt}	-	10	-	K
Input current protection mode	$I_{IN(Prot)}$	25	50	300	μA
Input current protection mode $T_j = 150\ ^\circ\text{C}$	$I_{IN(Prot)}$	-	40	300	
Unclamped single pulse inductive energy ²⁾ each channel $I_D = 0.9$ A, $T_j = 25\ ^\circ\text{C}$, $V_{bb} = 12$ V	E_{AS}	150	-	-	mJ

Inverse Diode

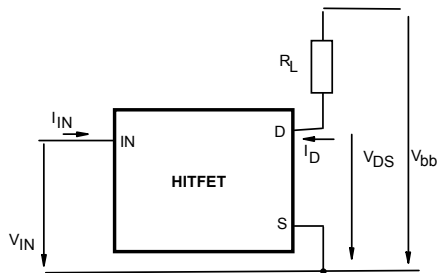
Inverse diode forward voltage $I_F = 7$ A, $t_m = 250\ \mu\text{s}$, $V_{IN} = 0$ V, $t_P = 300\ \mu\text{s}$	V_{SD}	-	1	-	V
--	----------	---	---	---	---

¹⁾ Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.

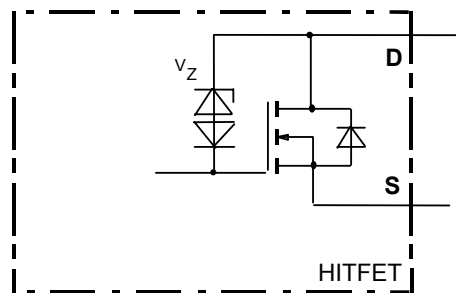
²⁾ not subject to production test, specified by design

Block diagram

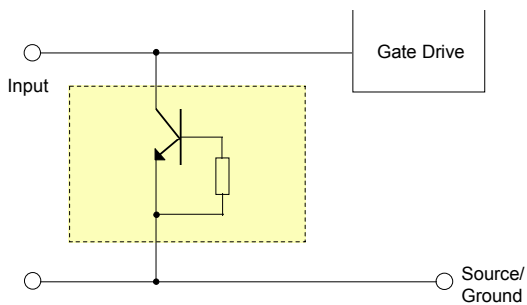
Terms



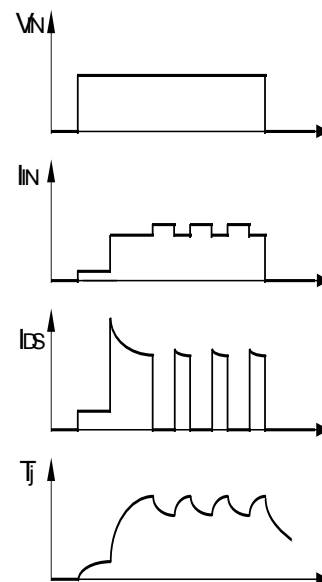
Inductive and overvoltage output clamp



Input circuit (ESD protection)

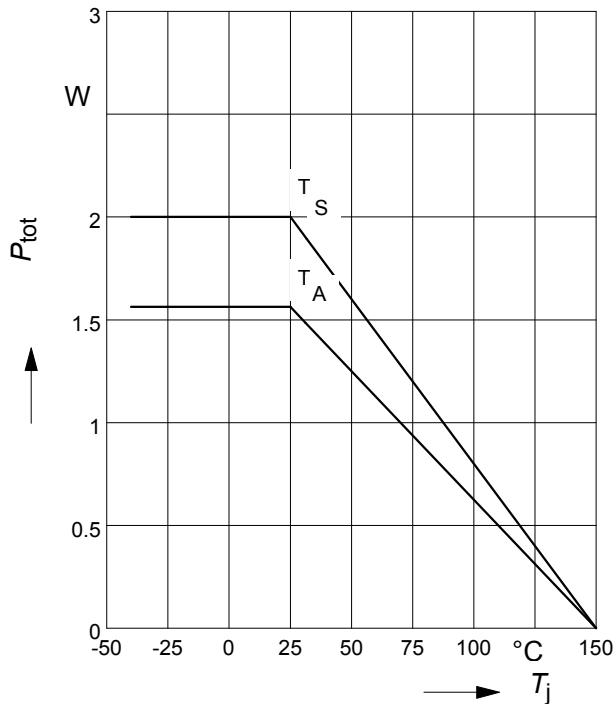


Short circuit behaviour



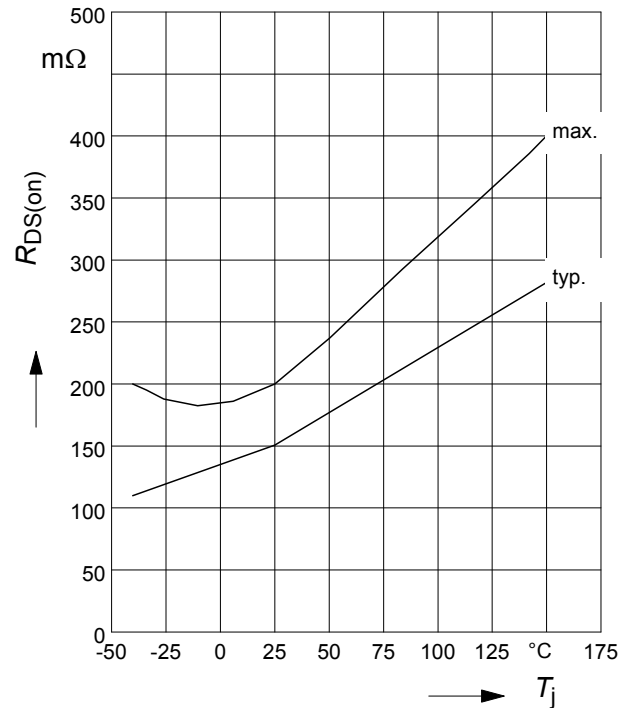
1 Overall maximum allowable power dissipation; $P_{\text{tot}} = f(T_S)$ resp.

$$P_{\text{tot}} = f(T_A) @ R_{\text{thJA}} = 80 \text{ K/W}$$



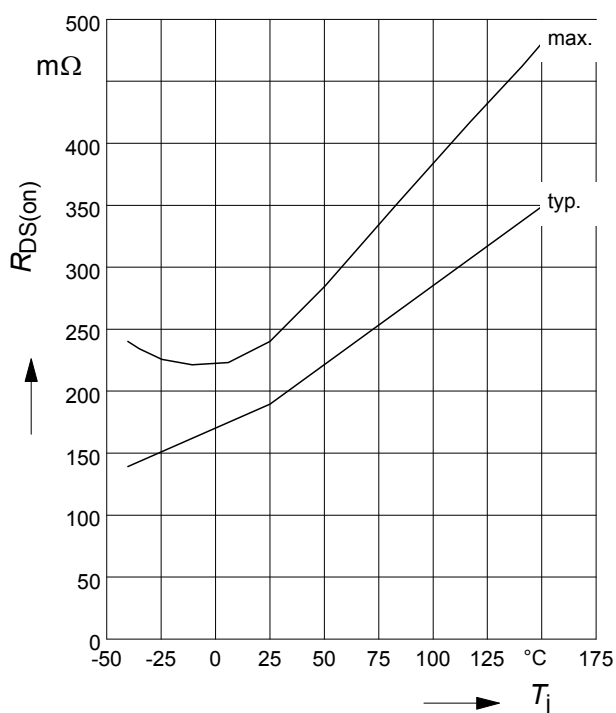
2 On-state resistance

$$R_{\text{ON}} = f(T_j); I_D = 1.4 \text{ A}; V_{\text{IN}} = 10 \text{ V}$$



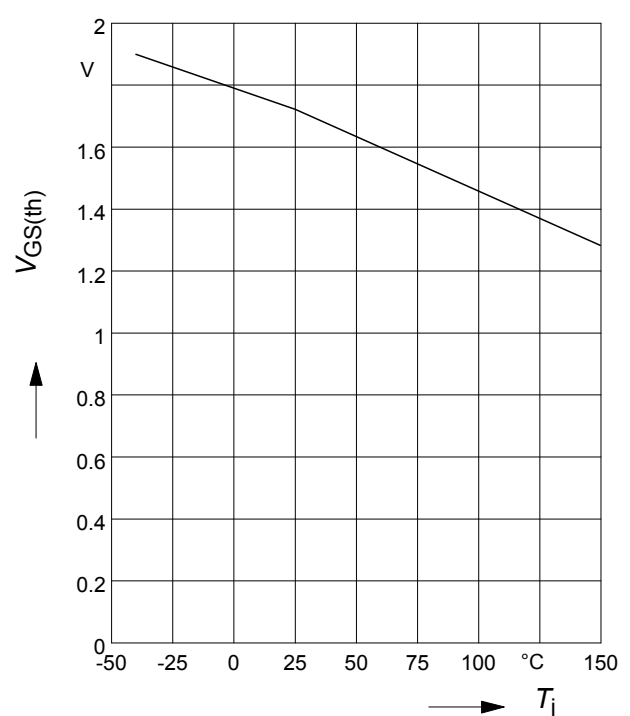
3 On-state resistance

$$R_{\text{ON}} = f(T_j); I_D = 1.4 \text{ A}; V_{\text{IN}} = 5 \text{ V}$$



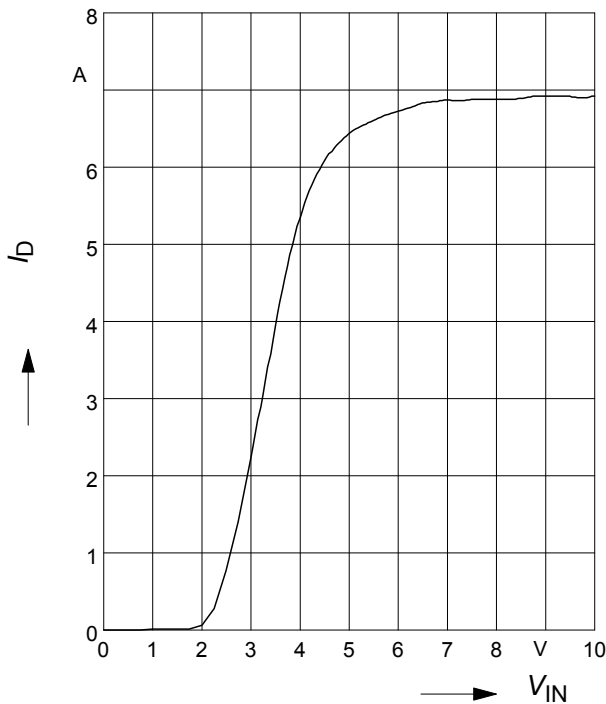
4 Typ. input threshold voltage

$$V_{\text{IN(th)}} = f(T_j); I_D = 0.15 \text{ mA}; V_{\text{DS}} = 12 \text{ V}$$



5 Typ. transfer characteristics

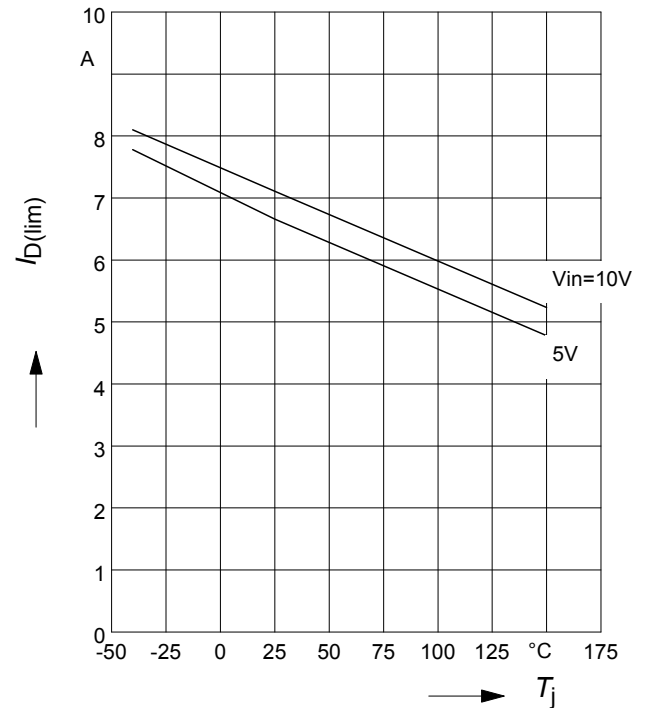
$I_D = f(V_{IN})$; $V_{DS} = 12V$; $T_{Jstart} = 25^\circ C$



6 Typ. short circuit current

$I_{D(lim)} = f(T_j)$; $V_{DS} = 12V$

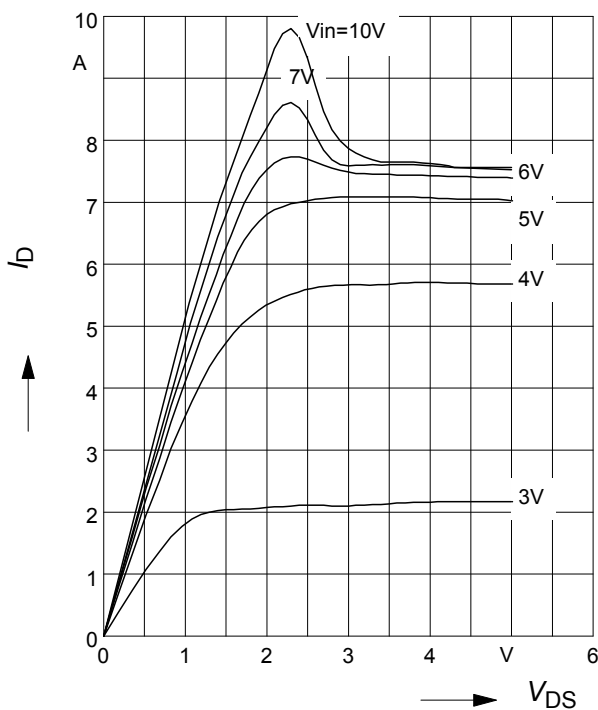
Parameter: V_{IN}



7 Typ. output characteristics

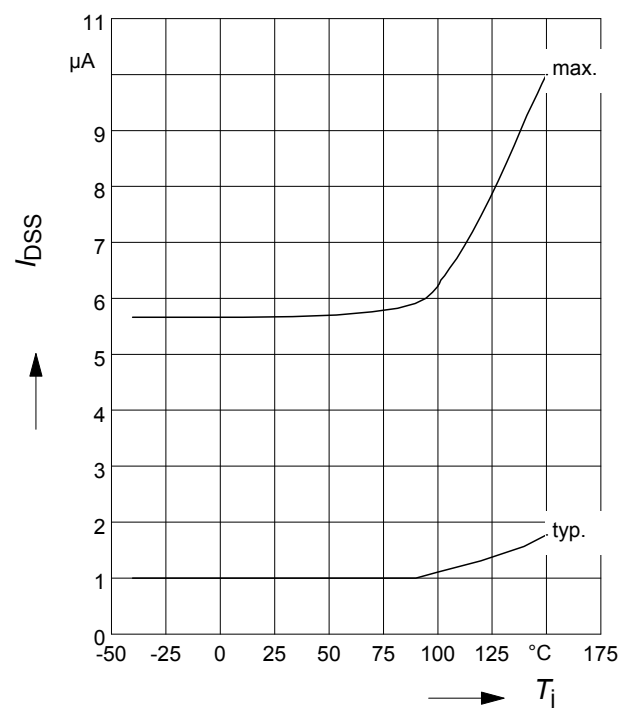
$I_D = f(V_{DS})$; $T_{Jstart} = 25^\circ C$

Parameter: V_{IN}



8 Typ. off-state drain current

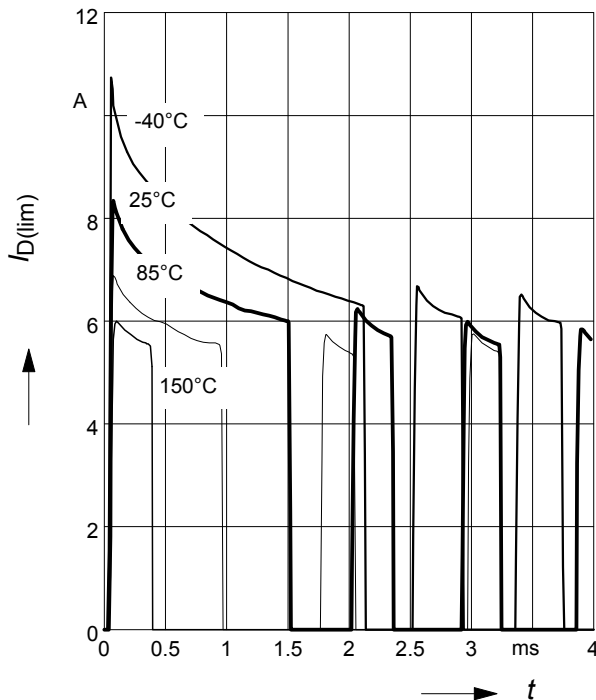
$I_{DSS} = f(T_j)$



9 Typ. overload current

$I_{D(lim)} = f(t)$, $V_{bb}=12\text{ V}$, no heatsink

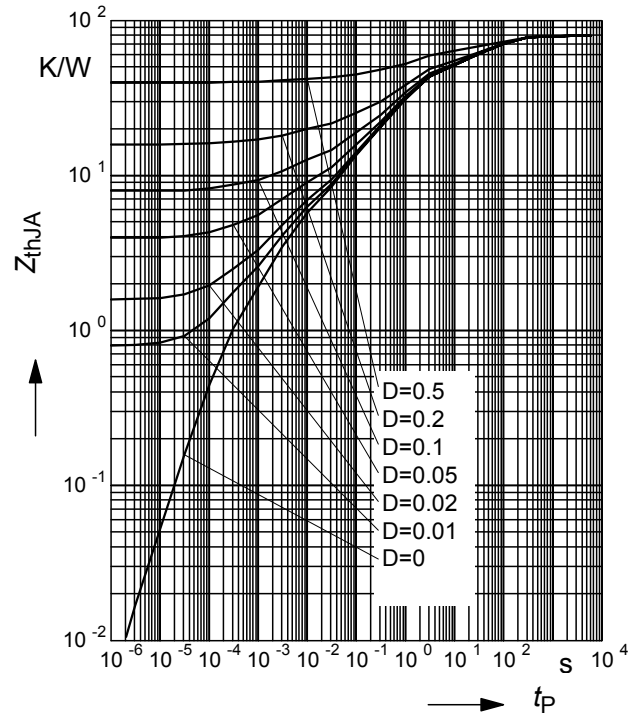
Parameter: T_{jstart}



10 Typ. transient thermal impedance

$Z_{thJA} = f(t_p)$ @ 6 cm^2 cooling area

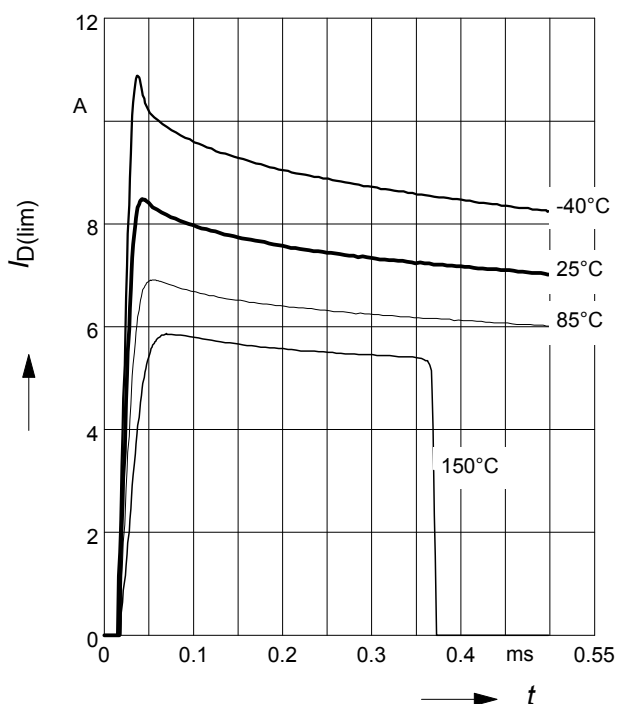
Parameter: $D = t_p/T$; one channel on



11 Determination of $I_{D(lim)}$

$I_{D(lim)} = f(t)$; $t_m = 200\mu\text{s}$

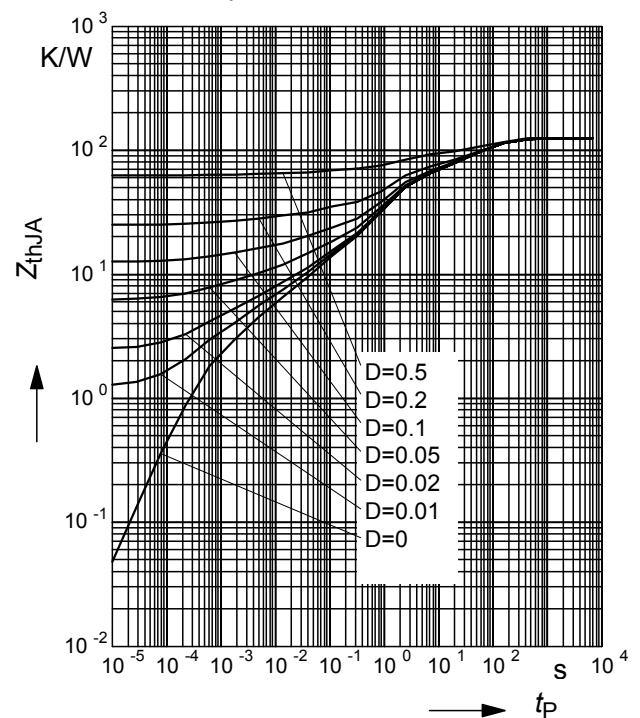
Parameter: T_{jstart}



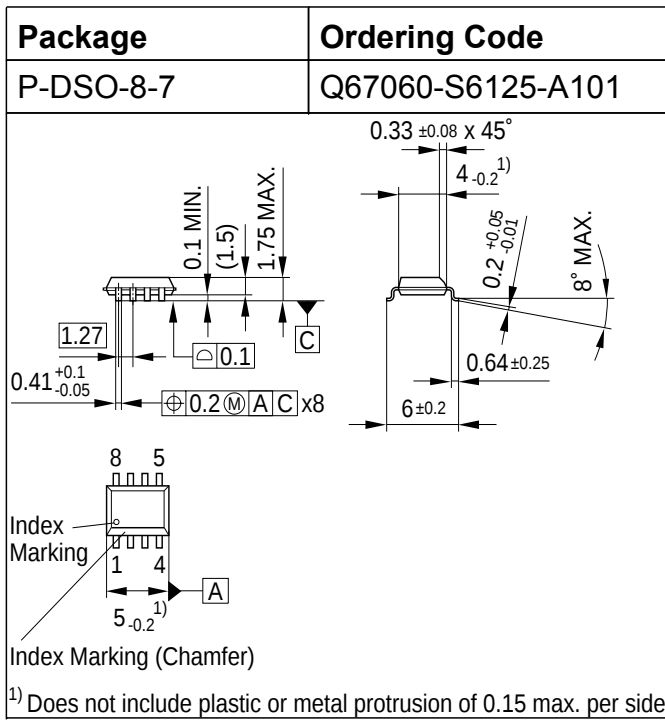
12 Typ. transient thermal impedance

$Z_{thJA} = f(t_p)$ @ 6 cm^2 cooling area

Parameter: $D = t_p/T$; both channels on



Package	Ordering Code
P-DSO-8-7	Q67060-S6125-A101



1) Does not include plastic or metal protrusion of 0.15 max. per side

Published by
Infineon Technologies AG,
St.-Martin-Strasse 53,
D-81669 München
© Infineon Technologies AG 2001
All Rights Reserved.

Attention please!

The information herein is given to describe certain components and shall not be considered as a guarantee of characteristics.

Terms of delivery and rights to technical change reserved.

We hereby disclaim any and all warranties, including but not limited to warranties of non-infringement, regarding circuits, descriptions and charts stated herein.

Infineon Technologies is an approved CECC manufacturer.

Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office in Germany or our Infineon Technologies Representatives worldwide (see address list).

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.